Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**A**

**C**

**.028”**

**.028”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: A = .007 X .015” C = .007 x .007”**

**Backside Potential: CATHODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .028” X .028” DATE: 8/26/21**

**MFG: MOTOROLA THICKNESS .008” P/N: 1N4572A**

**DG 10.1.2**

#### Rev B, 7/1